### PATENT ASSIGNMENT

## Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:			CORRECTIVE ASSIGNMENT					
NATURE OF CONVEYANCE:			Corrective Assignment to correct the assignment to re-record assignment previously recorded on Reel 025695 Frame 0105. Assignor(s) hereby confirms the correction of Patent No. 7779675 recorded in error to Patent No. 7799675.					
CONVEYING PARTY DATA								
		N	lame	Execution Date				
Sang-Yun Lee				12/15/2010				
RECEIVING PARTY DATA								
Name:	BeSang Inc.	BeSang Inc.						
Street Address:	1915 NW Am	bergle	n Pkwy.					
Internal Address:	Suite 310							
City:	Beaverton	Beaverton						
State/Country:	OREGON	OREGON						
Postal Code:	97006							
PROPERTY NUMBERS Total: 1								
Property T		Number						
Patent Number: 779		77996	575					
CORRESPONDENCE DATA								
Fax Number:	(480)655							
-			hen the fax attempt is unsuccessful.					
Email:	Phone:480 655-0073Email:jbrown@iplawusa.com							
Correspondent Name: Schmeiser Olsen & Watts LLP								
Address Line 1: 18 E. University Drive								
Address Line 2: Suite 101								
Address Line 4: Mesa, ARIZONA 85201								
ATTORNEY DOCKET NUMBER:			BESA.12758					
NAME OF SUBMITTER:			Greg L. Martinez					
Total Attachments: 14 PATENT								

source=Assignment\_with\_Appendix30#page1.tif source=Assignment\_with\_Appendix30#page2.tif source=Notice of Non-Recordation of Document#page1.tif source=Notice of Non-Recordation of Document#page3.tif source=Notice of Non-Recordation of Document#page3.tif source=Notice of Non-Recordation of Document#page4.tif source=Notice of Non-Recordation of Document#page5.tif source=Notice of Non-Recordation of Document#page6.tif source=Notice of Non-Recordation of Document#page6.tif source=Notice of Non-Recordation of Document#page7.tif source=Notice of Non-Recordation of Document#page8.tif source=Notice Recordation w Correction#page1.tif source=Notice Recordation w Correction#page3.tif source=Notice Recordation w Correction#page3.tif source=Notice Recordation w Correction#page3.tif

#### ASSIGNMENT

I, Sang-Yun Lee, residing at 18082 NW Elk Run Drive, Beaverton, Oregon 97006, represent that I have invented improvements in new and useful semiconductor technology for which I have executed applications for Letters Patent of the United States of America, as indicated in a list of applications for Letters Patent and issued patents provided in the Appendix included herewith.

BeSang, Inc., a corporation organized and existing under the laws of the State of Oregon, having a place of business at 1915 NW AmberGlen Pkwy, Suite 310, Beaverton, OR 97006 (hereinafter called BeSang), desires to acquire the entire right, title and interest in the said applications and issued patents and inventions, and to any United States and foreign patents to be obtained therefor.

For valuable consideration, the receipt and legal sufficiency of which I acknowledge, I have sold and do hereby sell, assign, transfer and set over unto BeSang, its successors and assigns, the entire right, title and interest in and to the inventions and all improvements thereon. in and to the applications for Letters Patent and issued patents thereon, as listed in the Appendix, in and to applications pertaining to or based upon the inventions, applications and issued patents, as listed in the Appendix, including divisional and continuing applications and continuations-in-part, and in and to any and all Letters Patent which may be granted and issued on the inventions, applications, and issued patents, as listed in the Appendix, or any of them, in the United States of America, its territories and possessions, and in all countries foreign thereto. together with and including all priority rights based upon any and all applications and issued patents in the United States of America covered by this Assignment.

I also agree that I will, at the request of BeSang, execute any and all applications for letters patent for the inventions, execute any and all other papers and documents and do all other and further lawful acts that BeSang may deem necessary or desirable to obtain Letters Patent on the invention, to secure the grant of such Letters Patent and to protect and vest in BeSang the undivided interests in the right, title and interest in the invention, applications and Letters Patent.

I also authorize and empower BeSang, its successors and assigns to apply for and obtain, in its or their own names, Letters Patent for the invention before competent International Authorities and in any and all countries foreign to the United States in which applications for Letters Patent can be so made or letters patent so obtained.

Signature: <u>Inventor, Sang-Yun Lee</u>

Signed at: <u>Beaverton, Oregon</u>. <u>December</u> <u>15</u>, 2010 Date

Page 1 of 1

# Appendix

	Patent No.	App. No.	Title	
$\frac{1}{2}$	7.378,702	10/934,270	Vertical Memory Device Structures	
2	7,052,941	10/873,969	Method for Making a Three-Dimensional Integrated Circuit Structure	
3	7,633,162	11/092.521	Electronic Circuit with Embedded Memory	
4	7,470,598	11/092,499	Semiconductor Layer Structure and Method of Making the Same	
5 6	7.470,142	11/092,498	Wafer Bonding Method	
6		11/092,500	Semiconductor memory device	
7		11/092.501	Semiconductor bonding and layer transfer method	
8		11/180,286	Semiconductor Device with Base Support Structure	
9		11/378,059	Three-Dimensional Integrated Circuit Structure and Meth of Making Same	
10		11/606,523	Three-Dimensional Integrated Circuit Structure	
11		11/873,719	Electronic Circuit with Embedded Memory	
32	7.718,508	11/873,851	Semiconductor Bonding and Layer Transfer Method	
13		11/873,769	Semiconductor Memory Device	
14	7,800,199	12/040.642	Semiconductor Circun	
15	7.671.371	12/165,445	Semiconductor Layer Structure and Method of Making the Same	
16	7.846,814	12/165,475	Semiconductor Layer Structure and Method of Making the Same	
17	7.632.738	12/345,503	Wafer Bonding Method	
18		12/397,309	Semiconductor Circuit and Method of Fabricating the Same	
19		12/470,344	Bonded Semiconductor Structure and Method of Making the Same	
20	7.779.675	12/475,294	Bonded Semiconductor Structure and Method of Fabricating the Same	
21		12/581,722	Information Storage System Which includes a Bonded Semiconductor Structure	
22		12/618,542	Semiconductor Memory Device	
23		12/637,559	Electronic Circuit with Embedded Memory	
24		12/635,496	Method for Fabricating a Semiconductor Method Device	
25		12/847.374	Semiconductor Circuit Structure and Method of Making the Same	
26		12/874,866	Semiconductor Circuit	
27		12/731,087	Three-Dimensional Semiconductor Structure and Method of Manufacturing the Same	
28		61/346,847	Semiconductor Circuit and Method of Forming the Semiconductor Circuit Using a Capping Layer	
29		61/349,134	Bonded Memory Circuit and Method of Pabrication	
30		12/847,244	Semiconductor Circuit Structure and Method of Forming the Same Using a Capping Layer	

Page 2 of 2

PATENT Ce REEL: 025879 FRAME: 0924

USPTO

2/7/2011 9:00:28 PM PAGE 3/008 Fax Server

D:ALBERT L. SCHMEISER COMPANY:18 E. UNIVERSITY DRIVE

## PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:		CORRECTIVE ASSIGNMENT					
NATURE OF CONVEYANCE:		assignment previously recorded on Re hereby confirms the to correct the pro	Corrective Assignment to correct the Corrective assignment to re-record assignment previously recorded on Reel 025695 Frame 0105. Assignor(s) hereby confirms the to correct the property on page 4 Application number, Filing Date, Patent number, Issue Date and Title.				
CONVEYING PARTY DATA							
	~~~~~~	Name	Execution Date				
Sang-Yun Lee			12/15/2010				
RECEIVING PARTY DATA							
Name:	BeSang, Inc.						
Street Address:	1915 AmberGlen Pkwy.						
Internal Address:	Suite 310						
City:	Beaverton						
State/Country:	OREGON						
Postal Code:	97006						
PROPERTY NUMBERS Total: 1							
Property Type		Number	Number				
Patent Number: 7799		7799675					

### USPTO

D:ALBERT L. SCHMEISER COMPANY:18 E. UNIVERSITY DRIVE

Total Attachments: 4 source≂Notice Recordation w Correction#page1.tif source≖Notice Recordation w Correction#page2.tif source=Notice Recordation w Correction#page3.tif source=Notice Recordation w Correction#page4.tif